

ABSTRACT

When exposing a same resist layer of a wafer W (W1 (or W2) a plurality of times, at least in one exposure of the plurality of exposures, by filling a space between a projection optical system, which projects an exposure light (IL) on the wafer (W1 (or W2)), and the wafer with water by a liquid supply/drainage unit, a substantial wavelength of exposure light (IL) that reaches the wafer is made to differ from a substantial wavelength of exposure light (IL) in another exposure. Accordingly, exposure with high precision and high throughput can be achieved.